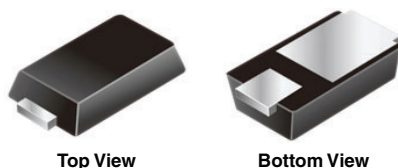


Ultrafast Rectifier, 2 A FRED Pt®

eSMP® Series



MicroSMP (DO-219AD)

Anode  Cathode

LINKS TO ADDITIONAL RESOURCES



FEATURES

- Very low profile - typical height of 0.65 mm
- Ideal for automated placement
- Low forward voltage drop, low power losses
- Low leakage current
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- For PFC, CRM snubber operation
- AEC-Q101 qualified
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912


RoHS
COMPLIANT
HALOGEN
FREE

TYPICAL APPLICATIONS

For use in high frequency, freewheeling, DC/DC converters, PFC, and in snubber industrial and automotive applications.

MECHANICAL DATA

Case: MicroSMP (DO-219AD)

Molding compound meets UL 94 V-0 flammability rating

Terminals: matte tin plated leads, solderable per J-STD-002, meets JESD 201 class 2 whisker test

Polarity: color band denotes cathode end

PRIMARY CHARACTERISTICS

$I_{F(AV)}$	2 A
V_R	100 V, 200 V
V_F at I_F	0.82 V
t_{rr} (typ.)	33 ns
I_{FSM}	30 A
T_J max.	175 °C
Package	MicroSMP (DO-219AD)
Circuit configuration	Single

ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Peak repetitive reverse voltage	V_{RRM}		100	V
			200	
Average rectified forward current	$I_{F(AV)}$	$T_M = 137\text{ °C}$	2	A
Non-repetitive peak surge current	I_{FSM}	$T_J = 25\text{ °C}$, 10 ms sine pulse	30	
Operating junction and storage temperatures	T_J, T_{Stg}		-55 to +175	°C

ELECTRICAL SPECIFICATIONS ($T_J = 25\text{ °C}$ unless otherwise specified)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Breakdown voltage, blocking voltage	V_{BR}, V_R	$I_R = 100\text{ }\mu\text{A}$	100	-	-	V
			200			
Forward voltage	V_F	$I_F = 2\text{ A}$	-	0.96	1.05	
		$I_F = 2\text{ A}, T_J = 150\text{ °C}$	-	0.82	0.84	
Reverse leakage current	I_R	$V_R = V_R$ rated	-	-	1	μA
		$T_J = 150\text{ °C}, V_R = V_R$ rated	-	-	25	
Junction capacitance	C_T	$V_R = 200\text{ V}$	-	6	-	pF

DYNAMIC RECOVERY CHARACTERISTICS ($T_J = 25^\circ\text{C}$ unless otherwise specified)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Reverse recovery time	t_{rr}	$I_F = 1.0\text{ A}$, $dI_F/dt = 50\text{ A}/\mu\text{s}$, $V_R = 30\text{ V}$	-	33	-	ns
		$I_F = 0.5\text{ A}$, $I_R = 1\text{ A}$, $I_{rr} = 0.25\text{ A}$	-	-	23	
		$T_J = 25^\circ\text{C}$	-	19	-	
		$T_J = 125^\circ\text{C}$	-	33	-	
Peak recovery current	I_{RRM}	$T_J = 25^\circ\text{C}$	-	1.7	-	A
		$T_J = 125^\circ\text{C}$	-	2.5	-	
Reverse recovery charge	Q_{rr}	$T_J = 25^\circ\text{C}$	-	15	-	nC
		$T_J = 125^\circ\text{C}$	-	34	-	

THERMAL - MECHANICAL SPECIFICATIONS						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Maximum junction and storage temperature range	T _J , T _{Stg}		-55	-	175	°C
Thermal resistance, junction to mount	R _{thJM} ⁽¹⁾		-	16	20	°C/W
Thermal resistance, junction to ambient	R _{thJA}	Device mounted on FR4 PCB, 2 oz. standard footprint	-	160	-	
Marking device	VS-2EQH01HM3	Case style MicroSMP (DO-219AD)	2H1			
	VS-2EQH02HM3		2H2			

Note

(1) Thermal resistance junction to mount follows JEDEC® 51-14 transient dual interface test method (TDIM)

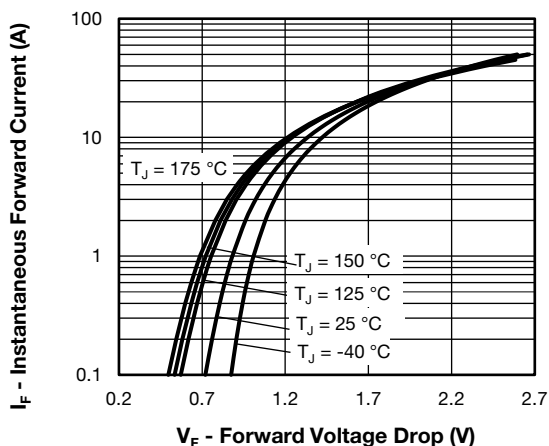


Fig. 1 - Typical Forward Voltage Drop Characteristics

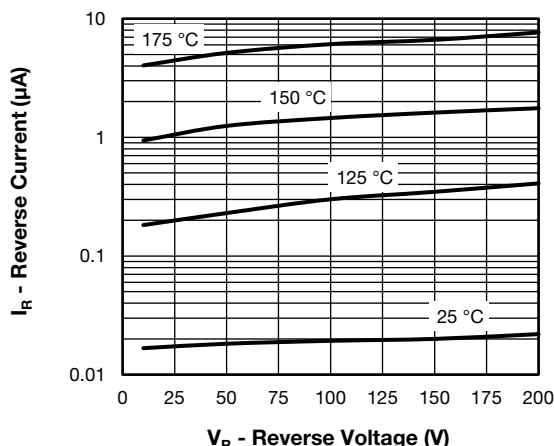


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

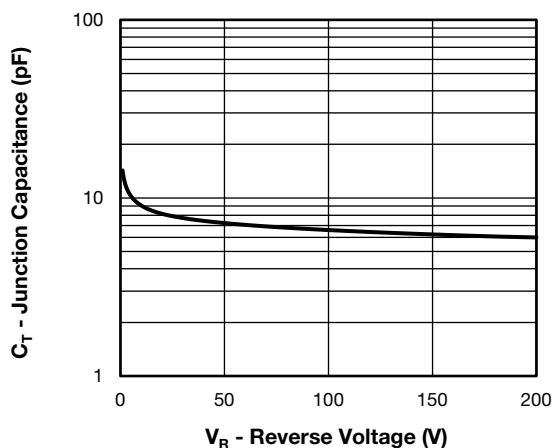


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

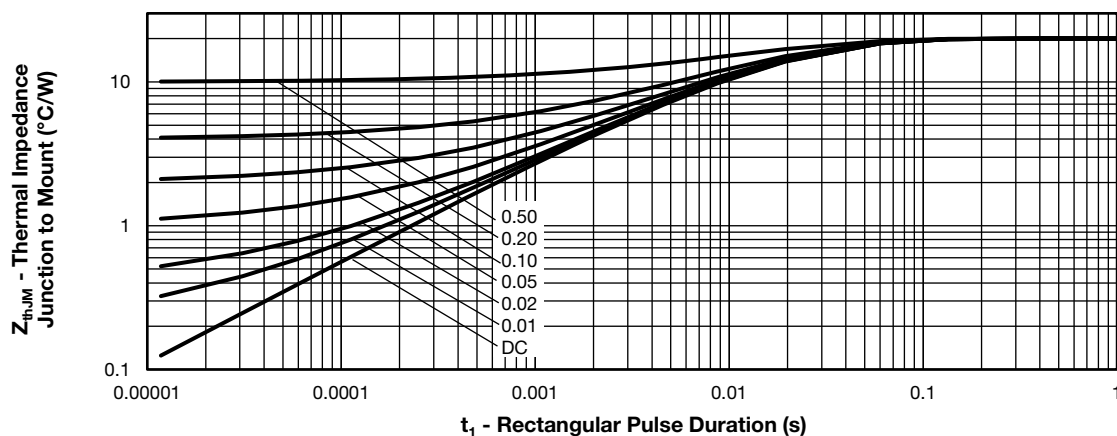


Fig. 4 - Maximum Transient Thermal Impedance, Junction to Mount

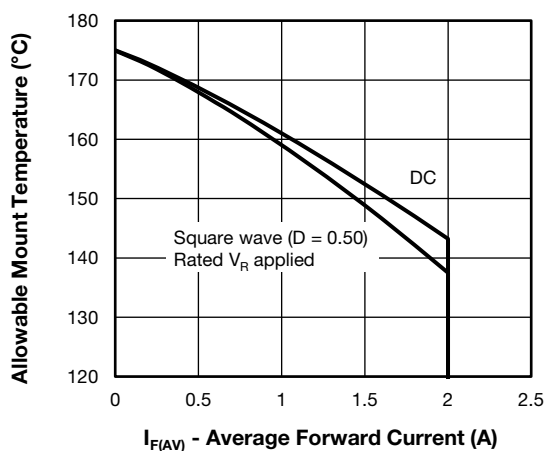


Fig. 5 - Maximum Allowable Mount Temperature vs. Average Forward Current

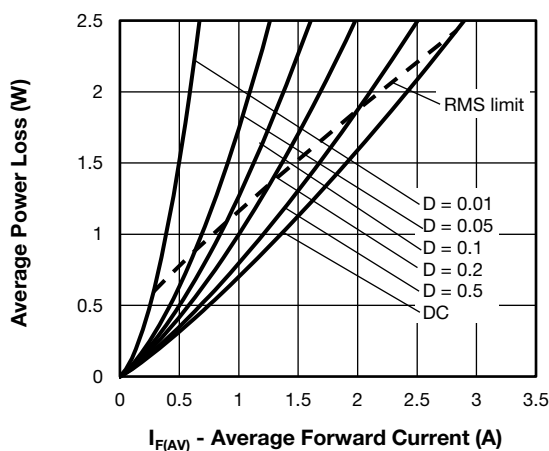


Fig. 6 - Forward Power Loss Characteristics

Note

Formula used: $T_M = T_J - (P_d + P_{dREV}) \times R_{thJM}$;

P_d = forward power loss = $I_{F(AV)} \times V_{FM}$ at $(I_{F(AV)}/D)$ (see fig. 5);

P_{dREV} = inverse power loss = $V_{R1} \times I_R (1 - D)$; I_R at V_{R1} = rated V_R

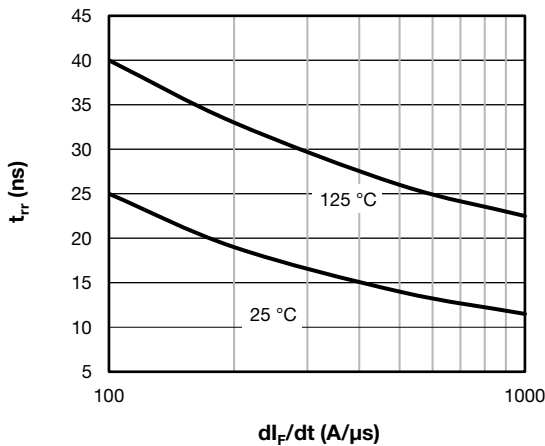
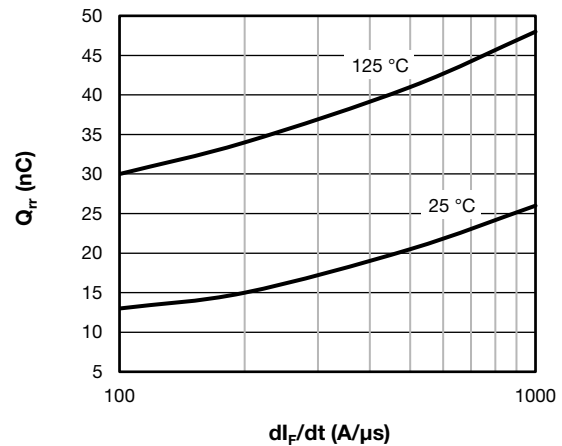
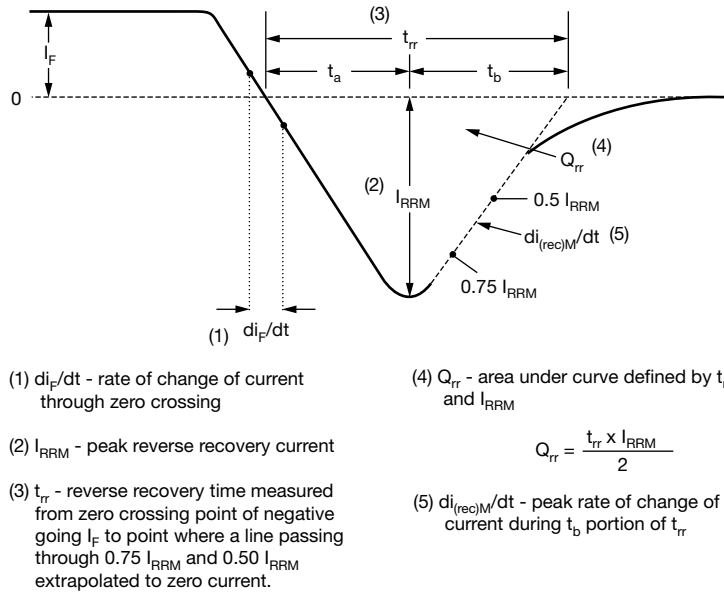

Fig. 7 - Typical Reverse Recovery Time vs. di_F/dt

Fig. 8 - Typical Stored Charge vs. di_F/dt


Fig. 9 - Reverse Recovery Waveform and Definitions



ORDERING INFORMATION TABLE

Device code	VS-	2	E	Q	H	02	H	M3
	1	2	3	4	5	6	7	8

- 1** - Vishay Semiconductors product
- 2** - Current rating (2 = 2 A)
- 3** - Circuit configuration:
E = single diode
- 4** - Q = MicroSMP package
- 5** - Process type,
H = ultrafast recovery
- 6** - Voltage code (02 = 200 V)
- 7** - H = AEC-Q101 qualified
- 8** - M3 = halogen-free, RoHS-compliant, and terminations lead (Pb)-free

ORDERING INFORMATION (Example)

PREFERRED P/N	PREFERRED PACKAGE CODE	MINIMUM ORDER QUANTITY	PACKAGING DESCRIPTION
VS-2EQH01HM3/H	H	4500	7" diameter plastic tape and reel
VS-2EQH02HM3/H	H	4500	7" diameter plastic tape and reel

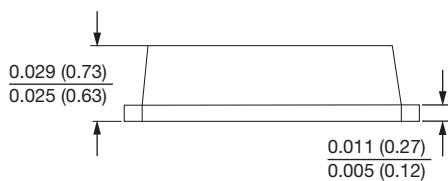
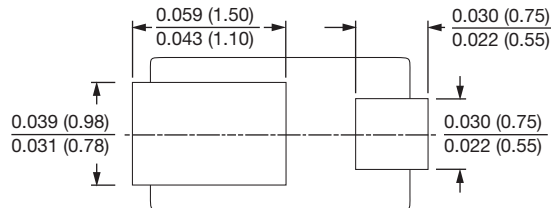
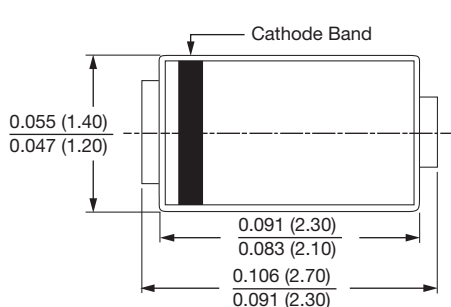
LINKS TO RELATED DOCUMENTS

Dimensions	www.vishay.com/doc?96591
Part marking information	www.vishay.com/doc?96590
Packaging information	www.vishay.com/doc?88869
SPICE model	www.vishay.com/doc?96595

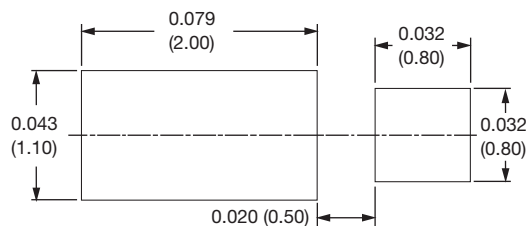


MicroSMP (DO-219AD), FRED Pt®

DIMENSIONS in inches (millimeters)



Mounting Pad Layout





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